PETLIN (MALAYSIA) SDN BHD (478535-T)

PRODUCT DATA SHEET



PETLIN LD C150Y

Low Density Polyethylene

PETLIN LD C150Y is a low density polyethylene resin for general purpose and thin film applications. It is produced by the state-of-the-art DSM Stamicarbon tubular process. It contains antioxidant (BHT free), slip and antiblock additives. It is intended primarily for blown film process.

Characteristics: low gels, high drawdown, high clarity, high gloss, good sealability, high slip,

high antiblocking.

Applications : thin gauge film for : textile, laundry, dry cleaning, garment ; crosslinked foams

; zip bags.

Recommended gauges : 15 - 60 microns

Extrusion Conditions : for blown film : melt temperature 145-165°C , recommended blow-up-ratio of

2 to 3:1

Typical Data : (25 microns film)

Properties		Units	Typical values	Test methods
Polymer properties :				
Melt Flow Rate: Density		dg/min kg/m³	5 921	ISO 1133 ISO 1183 (A)
Optical properties:				
Gloss (45°) Haze		‰ %	66 6.5	ASTM D2457 ASTM D1003A
<u>Mechanical properties</u> :				
Impact strength		g	86	ASTM D1709
Tear strength	TD MD	kN/m kN/m	30 80	ISO 6383-2
Tensile stress at break	TD MD	N/mm² N/mm²	15 26	ISO R527-3
Strain at break	TD MD	% %	610 149	ISO R527-3
Modulus of elasticity	TD MD	N/mm² N/mm²	224 202	ISO R527-3
Coefficient of friction		-	0.1	ASTM D1894

The properties shown above are typical values and are not to be taken as specifications.

Food contact approval status:

This material complies with FDA 21 CFR 177.1520 when used unmodified and according to good manufacturing practices for food contact applications. Accordingly, this material may be used in all food contact applications.

IMPORTANT NOTICE:

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